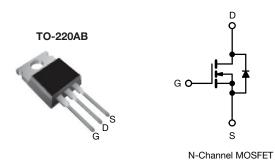
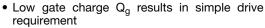


Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	500			
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	0.85		
Q _g max. (nC)	38			
Q _{gs} (nC)	9.0			
Q _{gd} (nC)	18			
Configuration	Single			

FEATURES





Improved gate, avalanche, and dynamic dV/dt ruggedness

- RoHS*
- Fully characterized capacitance and avalanche voltage and current
- Effective C_{oss} specified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptable power supply
- · High speed power switching

TYPICAL SMPS TOPOLOGIES

- Two transistor forward
- · Half bridge
- Full bridge

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF840APbF		
Lead (Pb)-free and halogen-free	IRF840APbF-BE3		

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	500	V	
Gate-source voltage			V_{GS}	± 30	v	
Continuous drain current	\/ at 10.\/	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		8.0		
	V _{GS} at 10 V	T _C = 100 °C	I _D	5.1	A	
Pulsed drain current ^a			I _{DM}	32		
Linear derating factor				1.0	W/°C	
Single pulse avalanche energy b			E _{AS}	510	mJ	
Repetitive avalanche current a			I _{AR}	8.0	А	
Repetitive avalanche energy ^a			E _{AR}	13	mJ	
Maximum power dissipation	T _C =	25 °C	P_{D}	125	W	
Peak diode recovery dV/dt ^c			dV/dt	5.0	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) d	For 10 s			300	7	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 16 mH, R_q = 25 Ω , I_{AS} = 8.0 A (see fig. 12)
- c. $I_{SD} \le 8.0 \text{ A}$, $dI/dt \le 100 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_J \le 150 \,^{\circ}\text{C}$
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	1.0		

PARAMETER	SYMBOL	TEST	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.58	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		-	4.0	V
Gate-source leakage	I _{GSS}	V _G	$V_{GS} = \pm 30 \text{ V}$		-	± 100	nA
		$V_{DS} = 5$	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$		-	25	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 400 V, V	V _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 4.8 A ^b	-	-	0.85	Ω
Forward transconductance	9 _{fs}	V _{DS} = 5	0 V, I _D = 4.8 A ^b	3.7	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 V$,		-	1018	-	
Output capacitance	C _{oss}	V	_{DS} = 25 V,	-	155	-	1
Reverse transfer capacitance	C _{rss}	$f = 1.0 \text{ MHz, see fig. 5}$ $V_{GS} = 0 \text{ V; } V_{DS} = 1.0 \text{ V, f} = 1.0 \text{ MHz}$ $V_{GS} = 0 \text{ V; } V_{DS} = 400 \text{ V, f} = 1.0 \text{ MHz}$ $V_{GS} = 0 \text{ V; } V_{DS} = 0 \text{ V to } 400 \text{ V}^{c}$		-	8.0	-	pF
Output capacitance	C _{oss}				1490		
Output capacitance	C _{oss}				42		
Effective output capacitance	Coss eff.				56		
Total gate charge	Q_g			-	-	38	nC
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 8 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 b	-	-	9.0	
Gate-drain charge	Q _{gd}		See lig. 6 and 16	-	-	18	
Turn-on delay time	t _{d(on)}			-	11	-	
Rise time	t _r	$V_{DD} =$	$V_{DD} = 250 \text{ V}, I_D = 8 \text{ A}$		23	-	- ns
Turn-off delay time	t _{d(off)}	$R_g = 9.1 \ \Omega$, $R_D = 31 \ \Omega$, see fig. 10 b		-	26	-	
Fall time	t _f			-	19	-	
Gate input resistance	R_g	f = 1 MHz, open drain		0.7	-	3.7	Ω
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	8.0	^
Pulsed diode forward current ^a	I _{SM}			-	-	32	A
Body diode voltage	V _{SD}	T _J = 25 °C, I _S = 8 A, V _{GS} = 0 V ^b		-	-	2.0	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 8 A, dl/dt = 100 A/μs b		-	422	633	ns
Body diode reverse recovery charge	Q _{rr}			-	2.16	3.24	μC
Forward turn-on time	t _{on}	Intrinsic turn	-on time is negligible (turr	-on is do	minated b	by L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

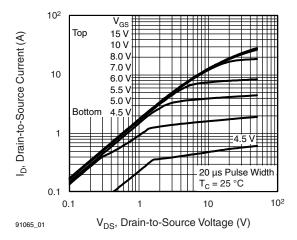


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

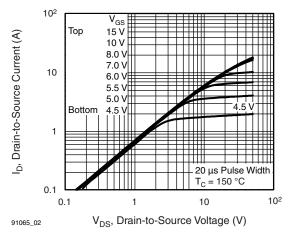


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

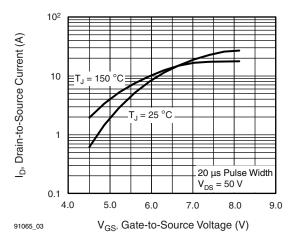


Fig. 3 - Typical Transfer Characteristics

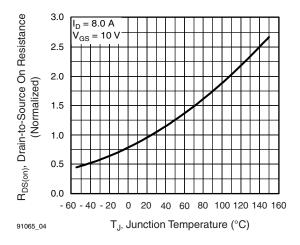


Fig. 4 - Normalized On-Resistance vs. Temperature

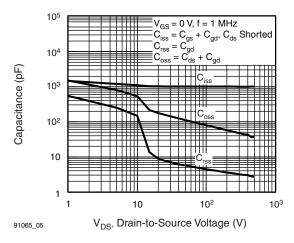


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

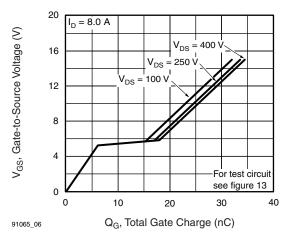


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



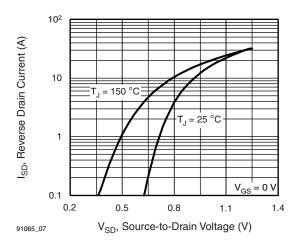


Fig. 7 - Typical Source-Drain Diode Forward Voltage

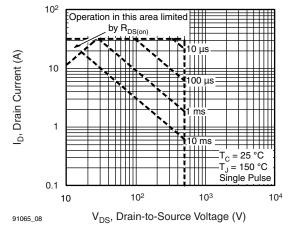


Fig. 8 - Maximum Safe Operating Area

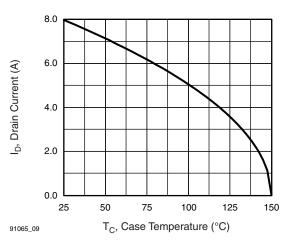


Fig. 9 - Maximum Drain Current vs. Case Temperature

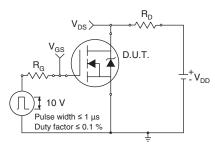


Fig. 10a - Switching Time Test Circuit

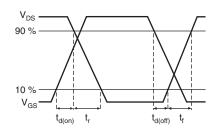


Fig. 10b - Switching Time Waveforms

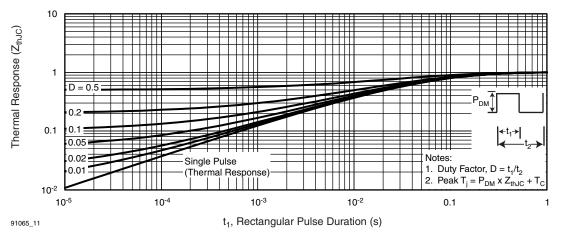


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



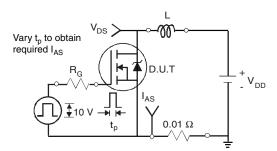


Fig. 12a - Unclamped Inductive Test Circuit

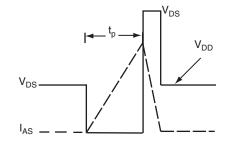


Fig. 12b - Unclamped Inductive Waveforms

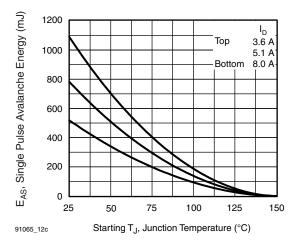


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

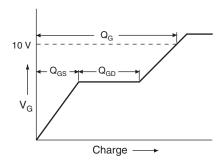


Fig. 12d - Basic Gate Charge Waveform

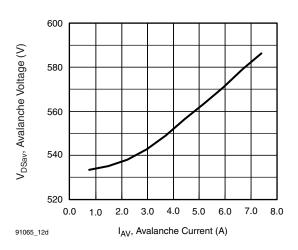


Fig. 13a - Typical Drain-to-Source Voltage vs. Avalanche Current

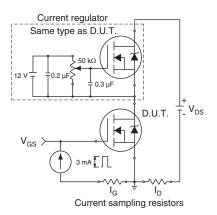
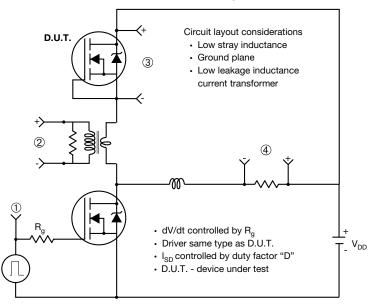


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



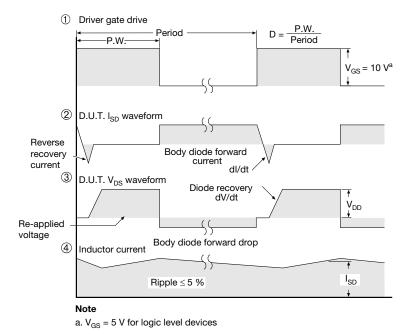


Fig. 14 - For N-Channel

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